



## WILAPLAT Electroforming Baths

### High Performance Electroforming Bright Copper Bath

For Electroforming

Article No. 3060400202

#### Description

Very ductile, bright, almost crack and stress-free layering is achieved with this sulphuric acid Copper Bath. Its high levelling power means that pre-polishing of the work pieces is not essential. Due to the thus significantly reduced surface roughness, this layer can be considered as a universal foundation for decorative coating in precious metals.

#### Application

The Copper Bath is for use in a conventional electro-plating unit such as the WILAPLAT-System. For extended process times (approx. 4Ah/litre) brightening agents must be added. The amount of brightening agent added depends on the extent to which the brightness has diminished. The ration between brightener 408 and 801 must be 1 : 3.5 (1 ml of brightener no. 408 means 3.5 ml of brightener no. 801 must be added). For larger bath volumes air injection is recommended as this will increase the anode solubility.

#### Operating Data

<b>Copper Content</b>	50-60 g/l
<b>Sulphuric Acid Content</b>	50-65 g/l
<b>Temperature</b>	20-30°C
<b>Voltage</b>	0.3-1.6 volts
<b>Current Density</b>	1.0-6.0 dm <sup>2</sup>
<b>pH Value</b>	<1
<b>Movement</b>	Movement of electrolyte or work pieces required
<b>Anodes</b>	Phosphorous Copper
<b>Tank Material</b>	Glass, porcelain, plastic (PE, PVC etc.)

#### Deposition Data

<b>Alloy Deposit</b>	99.8% Cu
<b>Hardness</b>	approx. 220 HV
<b>Deposition Rate</b>	1.18 g/Ah
<b>Density</b>	8.9 g/cm <sup>3</sup>
<b>Current Output</b>	100%
<b>Bath Density</b>	1.17 g/cm <sup>3</sup>



## High Performance Electroforming Bright Copper Bath - page 2

### Supply Form

Ready for use solution

### Regeneration

Not worthwhile

### Warning!

Chemicals and materials used in electro-plating techniques can be corrosive or poisonous. During use, storage, transportation and disposal the relevant guidelines must be observed.

For further information see the EEC Safety Data Sheets